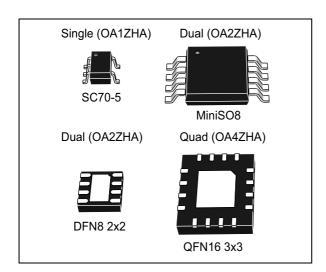


OA1ZHA, OA2ZHA, OA4ZHA

High precision 5 µV zero drift, low-power op amp

Datasheet - production data



Features

- Very high accuracy and stability: offset voltage 5 μV max at 25°C, 8 μV over full temperature range (-40°C to 125°C)
- Rail-to-rail input and output
- Low supply voltage: 1.8 5.5 V
- Low power consumption: 40 μA max. at 5 V
- Gain bandwidth product: 400 kHz
- High tolerance to ESD: 4 kV HBM
- Extended temperature range: -40 to +125°C
- Micro-packages: SC70-5, DFN8 2x2, and QFN16 3x3

Benefits

- High precision op amp without the need of calibration
- Accuracy virtually unaffected by temperature change

Applications

- Wearable
- · Fitness and healthcare
- Medical instrumentation

Description

The OA1ZHA, OA2ZHA, OA4ZHA series of low power, high precision op amp, offer very low input offset voltages with virtually zero drift.

OA1ZHA, OA2ZHA, OA4ZHA are respectively the single, dual and quad operational amplifier versions, with pinout compatible with industry standards.

The OA1ZHA, OA2ZHA, OA4ZHA series offers rail-to-rail input and output, excellent speed/power consumption ratio, and 400 kHz gain bandwidth product, while consuming less than 40 μ A at 5 V. All devices also feature an ultra-low input bias current.

The OA1ZHA, OA2ZHA, OA4ZHA family is the ideal choice for wearable, fitness and healthcare applications.

Table 1. Device summary

Order code	Temperature range	Package	Packaging	Marking
OA1ZHA22C	SC70-5	K44		
OA2ZHA22Q	40 to 1125 °C	DFN8 2x2	Tone and real	K33
OA2ZHA34S	-40 to +125 °C	MiniSO8	Tape and reel	K143
OA4ZHA33Q		QFN16 3x3		K193

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1 Package pin connections

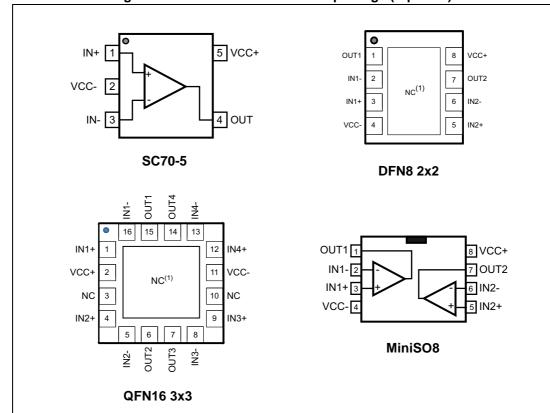


Figure 1. Pin connections for each package (top view)

1. The exposed pads of the DFN8 2x2 and the QFN16 3x3 can be connected to VCC- or left floating.

2 Absolute maximum ratings and operating conditions

Table 2. Absolute maximum ratings (AMR)

Symbol	Parameter	Value	Unit
V _{cc}	Supply voltage ⁽¹⁾	6	
V _{id}	Differential input voltage ⁽²⁾	±V _{cc}	V
V _{in}	Input voltage ⁽³⁾	V _{cc-} - 0.2 to V _{cc+} + 0.2	
I _{in}	Input current ⁽⁴⁾	10	mA
T _{stg}	Storage temperature	-65 to +150	°C
	Thermal resistance junction-to-ambient ⁽⁵⁾⁽⁶⁾		
	SC70-5	205	
R _{thja}	DFN8 2x2	57	°C/W
	MiniSO8	190	
	QFN16 3x3	39	
Tj	Maximum junction temperature	150	°C
	HBM: human body model, OA1ZHA only ⁽⁷⁾	4	kV
ESD	MM: machine model, OA1ZHA only ⁽⁸⁾	300	V
ESD	CDM: charged device model	1.5	kV
	CDM: charged device model, QFN16 3x3	TBD	\ \ \
	Latch-up immunity	200	mA

- 1. All voltage values, except differential voltage, are with respect to network ground terminal.
- 2. The differential voltage is the non-inverting input terminal with respect to the inverting input terminal.
- 3. V_{cc} V_{in} must not exceed 6 V, V_{in} must not exceed 6 V.
- 4. Input current must be limited by a resistor in series with the inputs.
- 5. Short-circuits can cause excessive heating and destructive dissipation.
- 6. R_{th} are typical values.
- 7. Human body model: 100 pF discharged through a 1.5 $k\Omega$ resistor between two pins of the device, done for all couples of pin combinations with other pins floating.
- Machine model: a 200 pF cap is charged to the specified voltage, then discharged directly between two
 pins of the device with no external series resistor (internal resistor < 5 Ω), done for all couples of pin
 combinations with other pins floating.

Table 3. Operating conditions

Symbol	Parameter	Value	Unit
V _{cc}	Supply voltage	1.8 to 5.5	V
V _{icm}	Common mode input voltage range	V_{cc-} - 0.1 to V_{cc+} + 0.1	V
T _{oper}	Operating free air temperature range	-40 to +125	°C



3 Electrical characteristics

 $V_{CC}+$ = 1.8 V with $V_{CC}-$ = 0 V, V_{icm} = $V_{CC}/2,$ T = 25 °C, and R_L = 10 $k\Omega$ connected to $V_{CC}/2$ (unless otherwise specified)

Table 4. Electrical characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
DC perfor	mance					
	la sud effect wells as	T = 25 °C		1	5	
V_{io}	Input offset voltage	-40 °C < T< 125 °C			8	μV
$\Delta V_{io}/\Delta T$	Input offset voltage drift ⁽¹⁾	-40 °C < T< 125 °C		10	30	nV/°C
	Input him ourrent ()/ // /2)	T = 25 °C		50	200 ⁽²⁾	
l _{ib}	Input bias current (V _{out} = V _{CC} /2)	-40 °C < T< 125 °C			300 ⁽²⁾	n ^
1	Input offset current ()/ -)/ /2)	T = 25 °C		100	400 ⁽²⁾	pA
l _{io}	Input offset current (V _{out} = V _{CC} /2)	-40 °C < T< 125 °C			600 ⁽²⁾	
	Common mode rejection ratio 20 log	T = 25 °C	110	122		
CMR	$ \begin{aligned} &(\Delta V_{icm}/\Delta V_{io}), \ V_{ic} = 0 \ V \ to \ V_{CC}, \\ &V_{out} = V_{CC}/2, \ R_L > 1 \ M\Omega \end{aligned} $	-40 °C < T< 125 °C	110			dB
Λ.	Large signal voltage gain	T = 25 °C	118	135		
A_{vd}	$V_{out} = 0.5 \text{ V to } (V_{cc} - 0.5 \text{ V})$	-40 °C < T< 125 °C	110			
V	High level output voltage	T = 25 °C			30	mV
V _{OH}		-40 °C < T< 125 °C			70	
V_{OL}	Low level output voltage	T = 25 °C			30	111 V
VOL	Low level output voltage	-40 °C < T< 125 °C			70	
	$I_{sink} (V_{out} = V_{CC})$	T = 25 °C	7	8		
1 .	Isink (Vout – VCC)	-40 °C < T< 125 °C	6			mA
l _{out}	I _{source} (V _{out} = 0 V)	T = 25 °C	5	7		ША
	source (vout = 0 v)	-40 °C < T< 125 °C	4			
	Supply current	T = 25 °C		28	40	
I _{CC}		-40 °C < T< 125 °C			40	μΑ
AC perfor	mance					
GBP	Gain bandwidth product			400		ld⊔⇒
F _u	Unity gain frequency			300		kHz
Φ_{m}	Phase margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		55		degrees
G _m	Gain margin			17		dB
SR	Slew rate ⁽³⁾			0.17		V/μs
t _s	Settling time	To 0.1%, $V_{in} = 1 \text{ Vp-p}$, $R_L = 10 \text{ k}\Omega$, $C_L = 100 \text{ pF}$		50		μs



Table 4. Electrical characteristics (continued)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
	Equivalent input noise voltage	f = 1 kHz		60		nV	
e _n	Equivalent input hoise voltage	f = 10 kHz		60		<u>nV</u> √Hz	
Cs	Channel separation	f = 100 Hz		120		dB	
		T = 25 °C		50		0	
t _{init}	Initialization time	-40 °C < T< 125 °C		100		μS	

^{1.} See Section 4.5: Input offset voltage drift over temperature. Input offset measurements are performed on x100 gain configuration. The amplifiers and the gain setting resistors are at the same temperature.

^{2.} Guaranteed by design.

^{3.} Slew rate value is calculated as the average between positive and negative slew rates.

 $V_{CC}+$ = 3.3 V with $V_{CC}-$ = 0 V, V_{icm} = $V_{CC}/2,$ T = 25 °C, and R_L = 10 $k\Omega$ connected to $V_{CC}/2$ (unless otherwise specified)

Table 5. Electrical characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
DC perfori	mance						
.,		T = 25 °C		1	5	.,	
V_{io}	Input offset voltage	-40 °C < T< 125 °C			8	μV	
ΔV _{io} /ΔΤ	Input offset voltage drift ⁽¹⁾	-40 °C < T< 125 °C		10	30	nV/°C	
,	Input bias current	T = 25 °C		60	200 ⁽²⁾		
I _{ib}	$(V_{out} = V_{CC}/2)$	-40 °C < T< 125 °C			300 ⁽²⁾	n 1	
-	Input offset current	T = 25 °C		120	400 ⁽²⁾	pА	
l _{io}	$(V_{\text{out}} = V_{\text{CC}}/2)$	-40 °C < T< 125 °C			600 ⁽²⁾		
	Common mode rejection ratio	T = 25 °C	115	128			
CMR	$ \begin{array}{l} 20 \ log \ (\Delta V_{icm}/\Delta V_{io}) \\ V_{ic} = 0 \ V \ to \ V_{CC}, \ V_{out} = V_{CC}/2 \\ R_L > 1 \ M\Omega \end{array} $	-40 °C < T< 125 °C	115			dB	
^	Large signal voltage gain	T = 25 °C	118	135			
A_{vd}	$V_{out} = 0.5 \text{ V to } (V_{cc} - 0.5 \text{ V})$	-40 °C < T< 125 °C	110				
V	Link level autout valtage	T = 25 °C			30	30	
V _{OH}	High level output voltage	-40 °C < T< 125 °C			70	m)/	
V	Lave lavel autout valtage	T = 25 °C			30	mV	
V_{OL}	Low level output voltage	-40 °C < T< 125 °C			70		
	1 (// -)/)	T = 25 °C	15	18			
	$I_{sink} (V_{out} = V_{CC})$	-40 °C < T< 125 °C	12			mA	
l _{out}	1 (\(\lambda \)	T = 25 °C	14	16		MA	
	I _{source} (V _{out} = 0 V)	-40 °C < T< 125 °C	10				
	Supply current	T = 25 °C		29	40		
I _{CC}	(per channel, $V_{out} = V_{CC}/2$, $R_L > 1 M\Omega$)	-40 °C < T< 125 °C			40	μΑ	
AC perfori	mance						
GBP	Gain bandwidth product			400		1.11_	
F _u	Unity gain frequency			300		kHz	
Φ_{m}	Phase margin	R_L = 10 kΩ, C_L = 100 pF		56		degrees	
G _m	Gain margin]		19		dB	
SR	Slew rate ⁽³⁾]		0.19		V/μs	
t _s	Settling time	To 0.1%, $V_{in} = 1 \text{ Vp-p}$, $R_L = 10 \text{ k}\Omega$, $C_L = 100 \text{ pF}$		50		μS	

Table 5. Electrical characteristics (continued)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
e _n	Equivalent input noise voltage	f = 1 kHz f = 10 kHz		40 40		$\frac{\text{nV}}{\sqrt{\text{Hz}}}$	
Cs	Channel separation	f = 100 Hz		120		dB	
ticit Initialization time		T = 25 °C		50		116	
t _{init}	illilialization time	-40 °C < T< 125 °C		100		μS	

^{1.} See Section 4.5: Input offset voltage drift over temperature. Input offset measurements are performed on x100 gain configuration. The amplifiers and the gain setting resistors are at the same temperature.

^{2.} Guaranteed by design.

^{3.} Slew rate value is calculated as the average between positive and negative slew rates.

 $V_{CC}+$ = 5 V with $V_{CC}-$ = 0 V, V_{icm} = $V_{CC}/2,$ T = 25 °C, and R_L = 10 $k\Omega$ connected to $V_{CC}/2$ (unless otherwise specified)

Table 6. Electrical characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
DC perform	nance							
\ /	land that will a	T = 25 °C		1	5	\ /		
V_{io}	Input offset voltage	-40 °C < T< 125 °C			8	μV		
$\Delta V_{io}/\Delta T$	Input offset voltage drift ⁽¹⁾	-40 °C < T< 125 °C		10	30	nV/°C		
1	Input bias current	T = 25 °C		70	200 ⁽²⁾			
l _{ib}	$(V_{out} = V_{CC}/2)$	-40 °C < T< 125 °C			300 ⁽²⁾	nΛ		
-	Input offset current	T = 25 °C		140	400 ⁽²⁾	рA		
l _{io}	$(V_{out} = V_{CC/2})$	-40 °C < T< 125 °C			600 ⁽²⁾			
	Common mode rejection ratio	T = 25 °C	115	136				
CMR	$ \begin{array}{l} 20 \ log \ (\Delta V_{icm}/\Delta V_{io}) \\ V_{ic} = 0 \ V \ to \ V_{CC/}, \ V_{out} = V_{CC}/\!\!/2 \\ R_L > 1 \ M\Omega \end{array} $	-40 °C < T< 125 °C	115					
	Supply voltage rejection ratio	T = 25 °C	120	140		dB		
SVR	$ \begin{aligned} &20 \log \left(\Delta V_{CC} / \Delta V_{io}\right) \\ &V_{CC} = 1.8 \text{ to } 5.5 \text{ V,} \\ &V_{out} = V_{CC} / 2, \text{ R}_L > 1 \text{ M}\Omega \end{aligned} $	-40 °C < T< 125 °C	120			uБ		
۸	Large signal voltage gain	T = 25 °C	120	135				
A_{vd}	$V_{out} = 0.5 \text{ V to } (V_{cc} - 0.5 \text{ V})$	-40 °C < T< 125 °C	110					
		$V_{RF} = 100 \text{ mV}_{p}, f = 400 \text{ MHz}$		84				
EMIRR ⁽³⁾	EMI rejection ratio EMIRR =	$V_{RF} = 100 \text{ mV}_{p}, f = 900 \text{ MHz}$		87		dB		
LIVIIIXIX	-20 log (V _{RFpeak} /∆V _{io})	$V_{RF} = 100 \text{ mV}_{p}, f = 1800 \text{ MHz}$		90		uБ		
		$V_{RF} = 100 \text{ mV}_{p}, f = 2400 \text{ MHz}$		91				
V_{OH}	High level output voltage	T = 25 °C			30			
VOH	Trigit level output voltage	-40 °C < T< 125 °C			70	mV		
V_{OL}	Low level output voltage	T = 25 °C			30	111.0		
VOL.	Low lover output voltage	-40 °C < T< 125 °C			70			
	$I_{sink} (V_{out} = V_{CC})$	T = 25 °C	15	18				
1	sink (vout = vCC/)	-40 °C < T< 125 °C	14			mA		
l _{out}	I _{source} (V _{out} = 0 V)	T = 25 °C	14	17		111/1		
	source (out = o v)	-40 °C < T< 125 °C	12					
	Supply current	T = 25 °C		31	40			
I _{CC}	(per channel, $V_{out} = V_{CC}/2$, $R_L > 1 M\Omega$)	-40 °C < T< 125 °C			40	μΑ		



Table 6. Electrical characteristics (continued)

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Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit		
AC perfori	nance							
GBP	Gain bandwidth product	B = 10 kO C = 100 pE		400		kHz		
F _u	Unity gain frequency	R_L = 10 kΩ, C_L = 100 pF		300		KIIZ		
Φ_{m}	Phase margin			53		degrees		
G _m	Gain margin	$R_L = 10 \text{ k}\Omega, C_L = 100 \text{ pF}$		19		dB		
SR	Slew rate ⁽⁴⁾			0.19		V/μs		
t _s	Settling time	To 0.1%, V_{in} = 100 mVp-p, R_L = 10 kΩ, C_L = 100 pF		10		μS		
e _n	Equivalent input noise voltage	f = 1 kHz f = 10 kHz		37 37		$\frac{\text{nV}}{\sqrt{\text{Hz}}}$		
C _s	Channel separation	f = 100 Hz		120		dB		
t _{init}	Initialization time	T = 25 °C		50				
	I IIIII alization time	-40 °C < T< 125 °C		100		μS		

^{1.} See Section 4.5: Input offset voltage drift over temperature. Input offset measurements are performed on x100 gain configuration. The amplifiers and the gain setting resistors are at the same temperature.

^{2.} Guaranteed by design.

^{3.} Tested on SC-70 package

^{4.} Slew rate value is calculated as the average between positive and negative slew rates.

Figure 2. Supply current vs. supply voltage

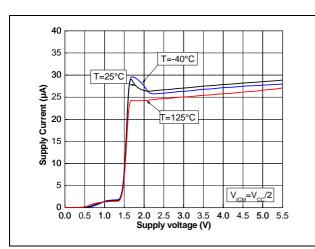


Figure 3. Input offset voltage distribution at $V_{CC} = 5 \text{ V}$

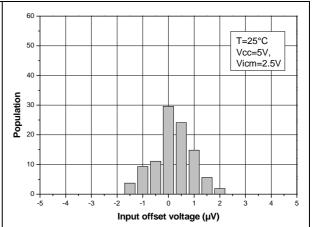


Figure 4. Input offset voltage distribution at $V_{CC} = 3.3 \text{ V}$

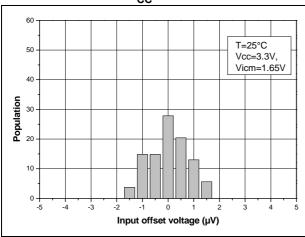


Figure 5. Input offset voltage distribution at $V_{CC} = 1.8 \text{ V}$

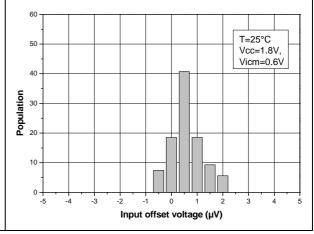


Figure 6. Vio temperature co-efficient distribution (-40 °C to 25 °C)

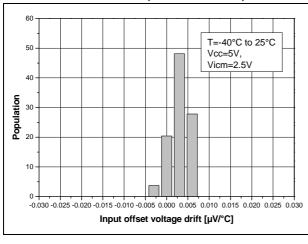


Figure 7. Vio temperature co-efficient distribution (25 °C to 125 °C)

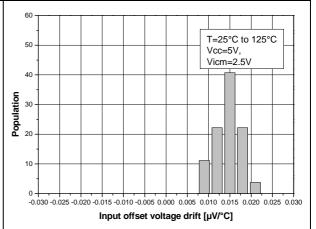


Figure 8. Input offset voltage vs. supply voltage Figure 9. Input offset voltage vs. input common mode at V_{CC} = 1.8 V

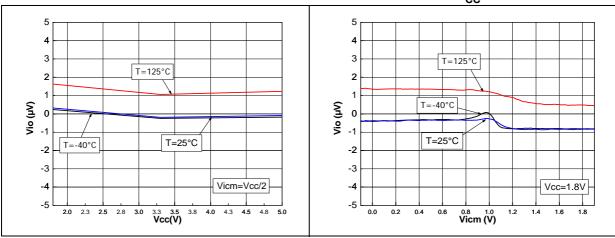


Figure 10. Input offset voltage vs. input common mode at $V_{CC} = 2.7 \text{ V}$

Figure 11. Input offset voltage vs. input common mode at V_{CC} = 5.5 V

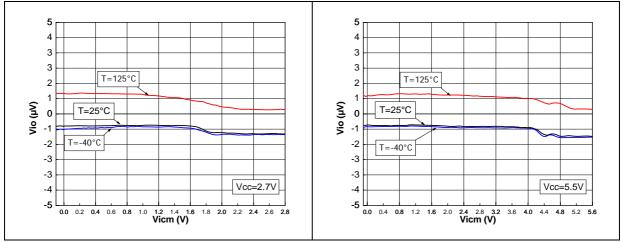


Figure 12. Input offset voltage vs. temperature

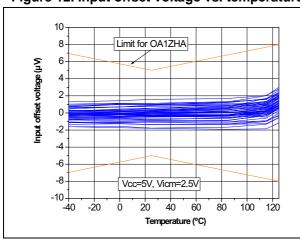
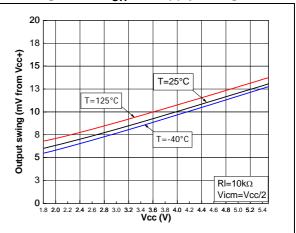


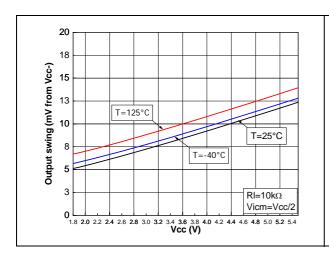
Figure 13. V_{OH} vs. supply voltage



7/

Figure 14. V_{OL} vs. supply voltage

Figure 15. Output current vs. output voltage at $V_{CC} = 1.8 \text{ V}$



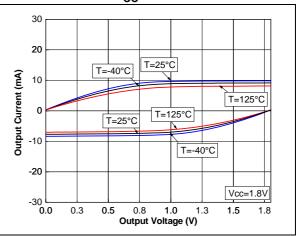
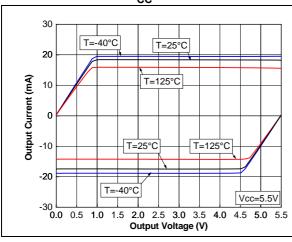


Figure 16. Output current vs. output voltage at $V_{CC} = 5.5 \text{ V}$

Figure 17. Input bias current vs. common mode at $V_{CC} = 5 \text{ V}$



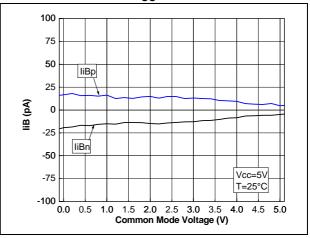
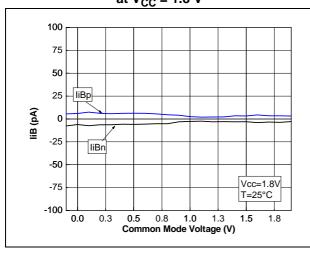


Figure 18. Input bias current vs. common mode Figure 19. Input bias current vs. temperature at at $V_{CC} = 1.8 \text{ V}$ $V_{CC} = 5 \text{ V}$



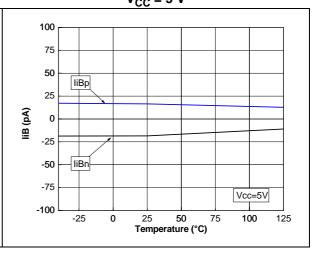




Figure 20. Bode diagram at V_{CC} = 1.8 V

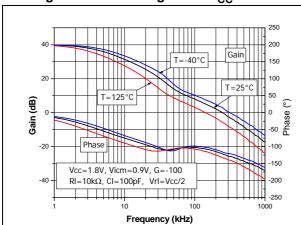


Figure 21. Bode diagram at $V_{CC} = 2.7 \text{ V}$

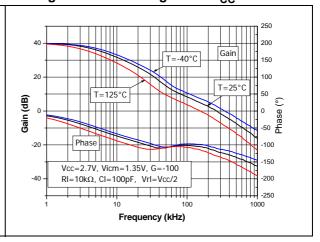


Figure 22. Bode diagram at $V_{CC} = 5.5 \text{ V}$

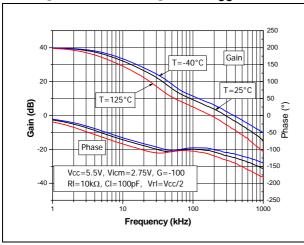


Figure 23. Open loop gain vs. frequency

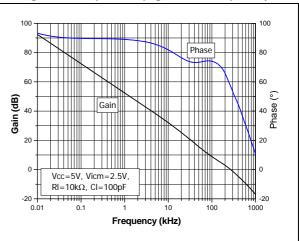
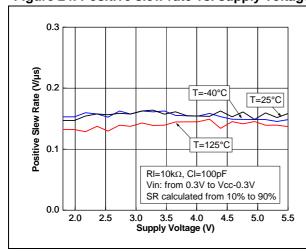
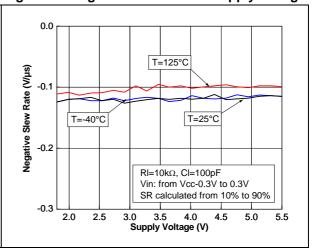


Figure 24. Positive slew rate vs. supply voltage Figure 25. Negative slew rate vs. supply voltage





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Figure 26. 0.1 Hz to 10 Hz noise

55 50 45 noise density (nV/√(Hz)) 40 35 30 25 20 Vcc = 5.5V Vicm=Vcc/2 Noise 0.1Hz_10Hz 15 T=25°C equivalent to 0.2 μVpp 100m 1 Frequency (Hz)

Figure 27. Noise vs. frequency

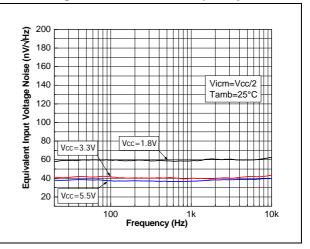
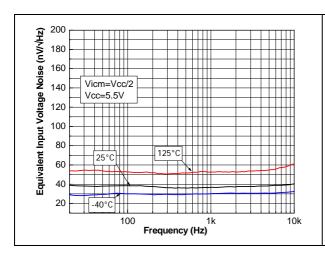


Figure 28. Noise vs. frequency and temperature

Figure 29. Output overshoot vs. load capacitance



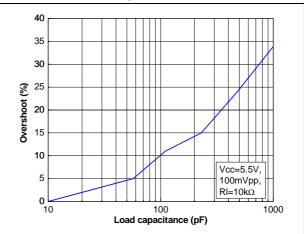


Figure 30. Small signal

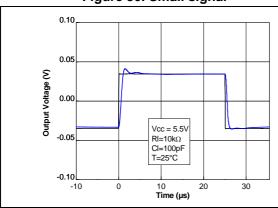


Figure 31. Large signal

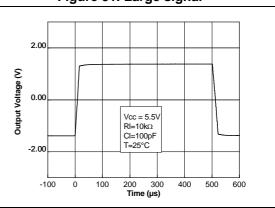


Figure 32. Positive overvoltage recovery at $V_{CC} = 1.8 \text{ V}$

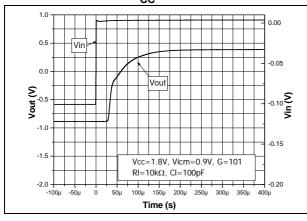


Figure 33. Positive overvoltage recovery at V_{CC} = 5 V

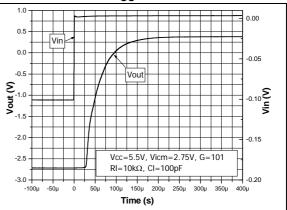


Figure 34. Negative overvoltage recovery at $V_{CC} = 1.8 \text{ V}$

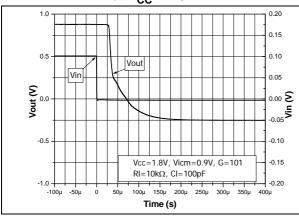


Figure 35. Negative overvoltage recovery at V_{CC} = 5 V

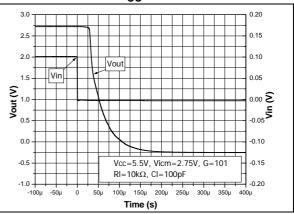


Figure 36. PSRR vs. frequency

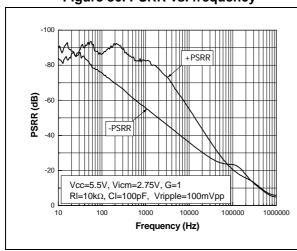
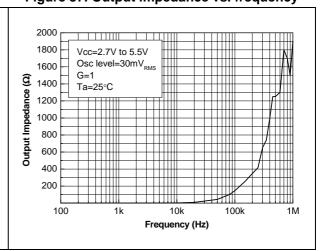


Figure 37. Output impedance vs. frequency



4 Application information

4.1 Operation theory

The OA1ZHA, OA2ZHA and OA4ZHA are high precision CMOS op amp. They achieve a low offset drift and no 1/f noise thanks to their chopper architecture. Chopper-stabilized amps constantly correct low-frequency errors across the inputs of the amplifier.

Chopper-stabilized amplifiers can be explained with respect to:

- Time domain
- Frequency domain

4.1.1 Time domain

The basis of the chopper amplifier is realized in two steps. These steps are synchronized thanks to a clock running at 400 kHz.

Figure 38. Block diagram in the time domain (step 1)

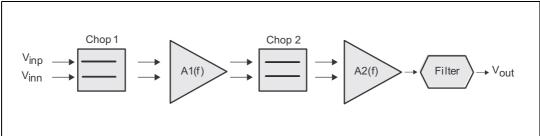


Figure 39. Block diagram in the time domain (step 2)

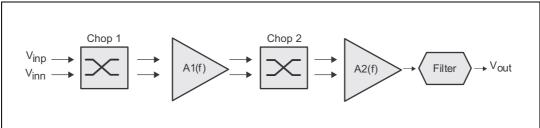


Figure 38 shows step 1, the first clock cycle, where V_{io} is amplified in the normal way.

Figure 39 shows step 2, the second clock cycle, where Chop1 and Chop2 swap paths. At this time, the V_{io} is amplified in a reverse way as compared to step 1.

At the end of these two steps, the average V_{io} is close to zero.

The A2(f) amplifier has a small impact on the V_{io} because the V_{io} is expressed as the input offset and is consequently divided by A1(f).

In the time domain, the offset part of the output signal before filtering is shown in Figure 40.

Step 1 Step 1

Vio Vio Step 2 Step 2

Step 2 Step 2

Figure 40. V_{io} cancellation principle

The low pass filter averages the output value resulting in the cancellation of the V_{io} offset.

The 1/f noise can be considered as an offset in low frequency and it is canceled like the V_{io} , thanks to the chopper technique.

4.1.2 Frequency domain

The frequency domain gives a more accurate vision of chopper-stabilized amplifier architecture.

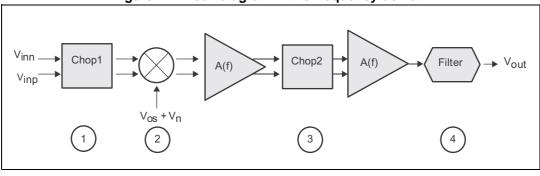


Figure 41. Block diagram in the frequency domain

The modulation technique transposes the signal to a higher frequency where there is no 1/f noise, and demodulate it back after amplification.

- 1. According to *Figure 41*, the input signal V_{in} is modulated once (Chop1) so all the input signal is transposed to the high frequency domain.
- 2. The amplifier adds its own error (V_{io} (output offset voltage) + the noise V_n (1/f noise)) to this modulated signal.
- 3. This signal is then demodulated (Chop2), but since the noise and the offset are modulated only once, they are transposed to the high frequency, leaving the output signal of the amplifier without any offset and low frequency noise. Consequently, the input signal is amplified with a very low offset and 1/f noise.
- 4. To get rid of the high frequency part of the output signal (which is useless) a low pass filter is implemented.

To further suppress the remaining ripple down to a desired level, another low pass filter may be added externally on the output of the OA1ZHA, OA2ZHA and OA4ZHA device.

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4.2 Operating voltages

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp can operate from 1.8 to 5.5 V. The parameters are fully specified for 1.8 V, 3.3 V, and 5 V power supplies. However, the parameters are very stable in the full V_{CC} range and several characterization curves show the OA1ZHA, OA2ZHA and OA4ZHA op amp characteristics at 1.8 V and 5.5 V. Additionally, the main specifications are guaranteed in extended temperature ranges from -40 to +125 $^{\circ}$ C.

4.3 Input pin voltage ranges

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp can operate from 1.8 to 5.5 V. The parameters are fully specified for 1.8 V, 3.3 V, an have internal ESD diode protection on the inputs. These diodes are connected between the input and each supply rail to protect the input MOSFETs from electrical discharge.

If the input pin voltage exceeds the power supply by 0.5 V, the ESD diodes become conductive and excessive current can flow through them. Without limitation this over current can damage the device.

In this case, it is important to limit the current to 10 mA, by adding resistance on the input pin, as described in *Figure 42*.

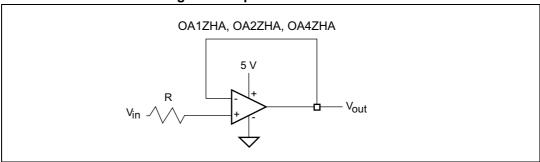


Figure 42. Input current limitation

4.4 Rail-to-rail input

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp have a rail-to-rail input, and the input common mode range is extended from V_{CC-} - 0.1 V to V_{CC+} + 0.1 V.

4.5 Input offset voltage drift over temperature

The maximum input voltage drift variation over temperature is defined as the offset variation related to the offset value measured at 25 °C. The operational amplifier is one of the main circuits of the signal conditioning chain, and the amplifier input offset is a major contributor to the chain accuracy. The signal chain accuracy at 25 °C can be compensated during production at application level. The maximum input voltage drift over temperature enables the system designer to anticipate the effect of temperature variations.

The maximum input voltage drift over temperature is computed using Equation 1.

Equation 1

$$\frac{\Delta V_{io}}{\Delta T} = \text{max} \left| \frac{V_{io}(T) - V_{io}(25^{\circ}C)}{T - 25^{\circ}C} \right|$$

where T = -40 °C and 125 °C.

The OA1ZHA, OA2ZHA and OA4ZHA CMOS datasheet maximum value is guaranteed by measurements on a representative sample size ensuring a C_{pk} (process capability index) greater than 1.3.

4.6 Rail-to-rail output

The operational amplifier output levels can go close to the rails: to a maximum of 30 mV above and below the rail when connected to a 10 k Ω resistive load to $V_{CC}/2$.

4.7 Capacitive load

Driving large capacitive loads can cause stability problems. Increasing the load capacitance produces gain peaking in the frequency response, with overshoot and ringing in the step response. It is usually considered that with a gain peaking higher than 2.3 dB an op amp might become unstable.

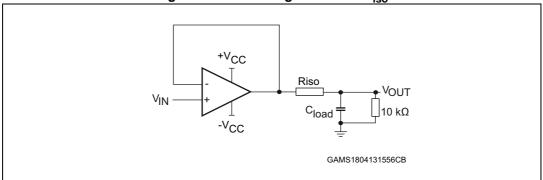
Generally, the unity gain configuration is the worst case for stability and the ability to drive large capacitive loads.

Figure 43 and *Figure 44* show the serial resistor that must be added to the output, to make a system stable. *Figure 45* shows the test configuration using an isolation resistor, R_{iso}.

10000 10000 Stable Stable Serial Resistor (Ohm) Serial Resistor (Ohm) 1000 1000 100 Unstable 100 Unstable Vcc=5V, Vicm=2.5V, T=25°C Vcc=1.8V, Vicm=0.9V, T=25°C RI=10 k Ω , G=1 RI=10 k Ω , G=1 10 100 0.1 1,000 Capacitive Load (nF) Capacitive Load (nF)

Figure 43. Stability criteria with a serial resistor Figure 44. Stability criteria with a serial resistor at $V_{DD} = 5 \text{ V}$ at $V_{DD} = 1.8 \text{ V}$

Figure 45. Test configuration for R_{iso}



4.8 PCB layout recommendations

Particular attention must be paid to the layout of the PCB, tracks connected to the amplifier, load, and power supply. The power and ground traces are critical as they must provide adequate energy and grounding for all circuits. Good practice is to use short and wide PCB traces to minimize voltage drops and parasitic inductance.

In addition, to minimize parasitic impedance over the entire surface, a multi-via technique that connects the bottom and top layer ground planes together in many locations is often used.

The copper traces that connect the output pins to the load and supply pins should be as wide as possible to minimize trace resistance.

4.9 Optimized application recommendation

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp are based on chopper architecture. As they are switched devices, it is strongly recommended to place a 0.1 μ F capacitor as close as possible to the supply pins.

A good decoupling has several advantages for an application. First, it helps to reduce electromagnetic interference. Due to the modulation of the chopper, the decoupling capacitance also helps to reject the small ripple that may appear on the output.

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp have been optimized for use with 10 k Ω in the feedback loop. With this, or a higher value of resistance, these devices offer the best performance.

4.10 EMI rejection ration (EMIRR)

The electromagnetic interference (EMI) rejection ratio, or EMIRR, describes the EMI immunity of operational amplifiers. An adverse effect that is common to many op amp is a change in the offset voltage as a result of RF signal rectification.

OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp have been specially designed to minimize susceptibility to EMIRR and show an extremely good sensitivity. *Figure 46* shows the EMIRR IN+ of the OA1ZHA, OA2ZHA and OA4ZHA measured from 10 MHz up to 2.4 GHz.

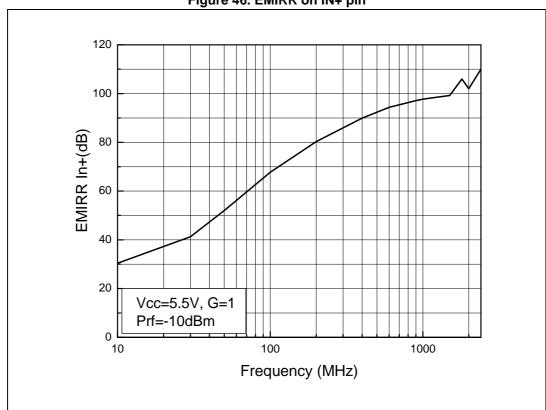


Figure 46. EMIRR on IN+ pin

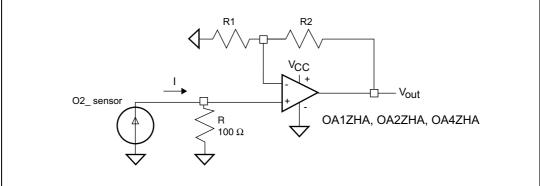
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4.11 Application examples

4.11.1 Oxygen sensor

The electrochemical sensor creates a current proportional to the concentration of the gas being measured. This current is converted into voltage thanks to *R* resistance. This voltage is then amplified by OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp (see *Figure 47*).

Figure 47. Oxygen sensor principle schematic



The output voltage is calculated using *Equation 2*:

Equation 2

$$V_{out} = (I \times R - V_{io}) \times \left(\frac{R_2}{R_1} + 1\right)$$

As the current delivered by the O2 sensor is extremely low, the impact of the V_{io} can become significant with a traditional operational amplifier. The use of the chopper amplifier of the OA1ZHA, OA2ZHA and OA4ZHA is perfect for this application.

In addition, using OA1ZHA, OA2ZHA and OA4ZHA op amp for the O2 sensor application ensures that the measurement of O2 concentration is stable even at different temperature thanks to a very good $\Delta V_{io}/\Delta T.$

4.11.2 Precision instrumentation amplifier

The instrumentation amplifier uses three op amp. The circuit, shown in *Figure 48*, exhibits high input impedance, so that the source impedance of the connected sensor has no impact on the amplification.

OA1ZHA R2 R4 OA4ZHA R2 OA4ZHA R3 OA2ZHA

Figure 48. Precision instrumentation amplifier schematic

The gain is set by tuning the R_g resistor. With R1 = R2 and R3 = R4, the output is given by *Equation 3*.

Equation 3

$$\boldsymbol{V}_{out} = (\boldsymbol{V}_2 - \boldsymbol{V}_1) \cdot \left[\frac{\boldsymbol{R}_4}{\boldsymbol{R}_2} \cdot \left(\frac{2\boldsymbol{R}_f}{\boldsymbol{R}_g} + 1 \right) \right]$$

The matching of R1, R2 and R3, R4 is important to ensure a good common mode rejection ratio (CMR).

4.11.3 Low-side current sensing

Power management mechanisms are found in most electronic systems. Current sensing is useful for protecting applications. The low-side current sensing method consists of placing a sense resistor between the load and the circuit ground. The resulting voltage drop is amplified using OA1ZHA, OA2ZHA and OA4ZHA CMOS op amp (see *Figure 49*).

Rg1 Rf1 Vout Vout OA1ZHA, OA2ZHA, OA4ZHA

Figure 49. Low-side current sensing schematic

Vout can be expressed as follows:

Equation 4

$$V_{out} = R_{shunt} \times I \bigg(1 - \frac{R_{g2}}{R_{g2} + R_{f2}} \bigg) \bigg(1 + \frac{R_{f1}}{R_{g1}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) \times \bigg(1 + \frac{R_{f1}}{R_{g1}} \bigg) - I_n \times R_{f1} - V_{io} \bigg(1 + \frac{R_{f1}}{R_{g1}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) \times \bigg(1 + \frac{R_{f1}}{R_{g1}} \bigg) - I_n \times R_{f1} - V_{io} \bigg(1 + \frac{R_{f1}}{R_{g1}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g1} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g1} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g1} \times R_{g2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g2} \times R_{f2}}{R_{g2} + R_{f2}} \bigg) + I_p \bigg(\frac{R_{g$$

Assuming that $R_{f2} = R_{f1} = R_f$ and $R_{g2} = R_{g1} = R_g$, *Equation 4* can be simplified as follows:

Equation 5

$$V_{out} = R_{shunt} \times I\left(\frac{R_f}{R_g}\right) - V_{io}\left(1 + \frac{R_f}{R_g}\right) + R_f \times I_{io}$$

The main advantage of using the chopper of the OA1ZHA, OA2ZHA and OA4ZHA, for a low-side current sensing, is that the errors due to V_{io} and I_{io} are extremely low and may be neglected.

Therefore, for the same accuracy, the shunt resistor can be chosen with a lower value, resulting in lower power dissipation, lower drop in the ground path, and lower cost.

Particular attention must be paid on the matching and precision of R_{g1} , R_{g2} , R_{f1} , and R_{f2} , to maximize the accuracy of the measurement.

5 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.



5.1 SC70-5 package information

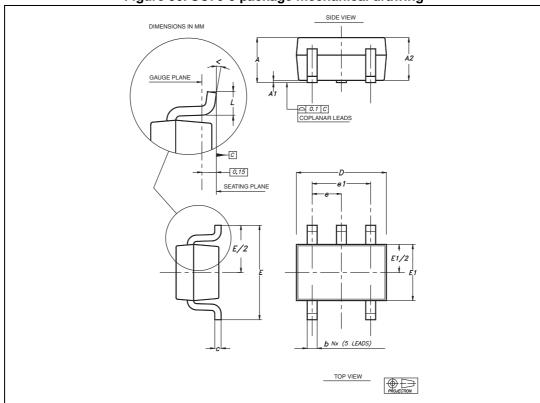


Figure 50. SC70-5 package mechanical drawing

Table 7. SC70-5 package mechanical data

		Dimensions							
Symbol		Millimeters		Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
Α	0.80		1.10	0.032		0.043			
A1	0		0.10			0.004			
A2	0.80	0.90	1.00	0.032	0.035	0.039			
b	0.15		0.30	0.006		0.012			
С	0.10		0.22	0.004		0.009			
D	1.80	2.00	2.20	0.071	0.079	0.087			
E	1.80	2.10	2.40	0.071	0.083	0.094			
E1	1.15	1.25	1.35	0.045	0.049	0.053			
е		0.65			0.025				
e1		1.30			0.051				
L	0.26	0.36	0.46	0.010	0.014	0.018			
<	0°		8°	0°		8°			

5.2 DFN8 2x2 package information

SEATING PLANE

C

PIN#1 ID

BOTTOM VIEW

AMS00019_V1

Figure 51. DFN8 2x2 package mechanical drawing

Table 8. DFN8 2x2x0.6 mm package mechanical data (pitch 0.5 mm)

		Dimensions								
Symbol		Millimeters			Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.				
Α	0.51	0.55	0.60	0.020	0.022	0.024				
A1			0.05			0.002				
A3		0.15			0.006					
b	0.18	0.25	0.30	0.007	0.010	0.012				
D	1.85	2.00	2.15	0.073	0.079	0.085				
D2	1.45	1.60	1.70	0.057	0.063	0.067				
E	1.85	2.00	2.15	0.073	0.079	0.085				
E2	0.75	0.90	1.00	0.030	0.035	0.039				
е		0.50			0.020					
L			0.425			0.017				
ddd			0.08			0.003				

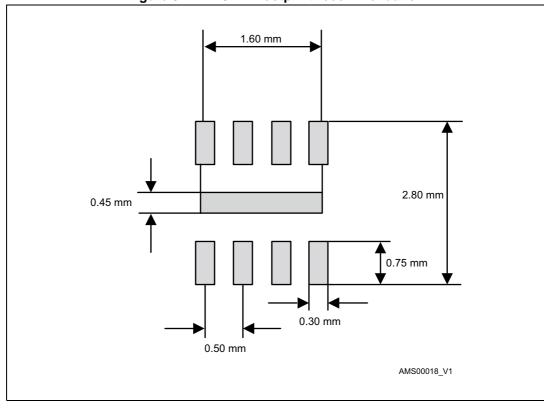


Figure 52. DFN8 2x2 footprint recommendation

5.3 MiniSO8 package information

PIN 1 IDENTIFICATION

SEATING PLANE

COUGE P

Figure 53. MiniSO8 package mechanical drawing

Table 9. MiniSO8 package mechanical data

	Dimensions							
Symbol		Millimeters		Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.		
Α			1.1			0.043		
A1	0		0.15	0		0.006		
A2	0.75	0.85	0.95	0.030	0.033	0.037		
b	0.22		0.40	0.009		0.016		
С	0.08		0.23	0.003		0.009		
D	2.80	3.00	3.20	0.11	0.118	0.126		
E	4.65	4.90	5.15	0.183	0.193	0.203		
E1	2.80	3.00	3.10	0.11	0.118	0.122		
е		0.65			0.026			
L	0.40	0.60	0.80	0.016	0.024	0.031		
L1		0.95			0.037			
L2		0.25			0.010			
k	0°		8°	0°		8°		
ccc			0.10			0.004		

5.4 QFN16 3x3 package information

BOTTOM VIEW R (OPTIONAL) EXPOSED PAD PIN 1 L 16x **b** 16x (4 LEADS PER SIDE) // 0.1 C SEATING PLANE Ċ 0.08 C LEADS COPLANARITY TOP VIEW GAMS1101131416CB

Figure 54. QFN16 3x3 package mechanical drawing

Table 10. QFN16 3 x 3 mm package mechanical data (pitch 0.5 mm)

	Dimensions							
Symbol	Millimeters			Inches				
	Min.	Тур.	Max.	Min.	Тур.	Max.		
Α	0.80	0.90	1.00	0.031	0.035	0.039		
A1	0		0.05	0		0.002		
А3		0.20			0.008			
b	0.18		0.30	0.007		0.012		
D	2.90	3.00	3.10	0.114	0.118	0.122		
D2	1.50		1.80	0.059		0.071		
Е	2.90	3.00	3.10	0.114	0.118	0.122		
E2	1.50		1.80	0.059		0.071		
е		0.50			0.020			
L	0.30		0.50	0.012		0.020		

6 Revision history

Table 11. Document revision history

Date	Revision	Changes
04-Mar-2014	1	Initial release.

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- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
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- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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